T298L



### N-Channel 100-V (D-S) 175 °C MOSFET

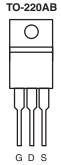
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	100			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0. 009			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0. 020			
I <sub>D</sub> (A)	100			
Configuration	Single			

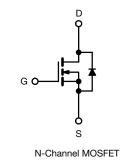
#### FEATURES

• TrenchFET<sup>®</sup> Power MOSFET



175 °C Maximum Junction Temperature
Compliant to RoHS Directive 2002/95/EC





ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	100	V		
Gate-Source Voltage			V <sub>GS</sub> ± 20		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	la.	100	A	
	T <sub>C</sub> = 125 °C	Ι <sub>D</sub>	75 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	300	A		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	75		
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 mm	E <sub>AS</sub>	280	mJ	
Maximum Power Dissipation <sup>b</sup>	$T_{C}$ = 25 °C (TO-220AB and TO-263)	PD	250 <sup>c</sup>	W	
	T <sub>A</sub> = 25 °C (TO-263) <sup>d</sup>	۰D	3.75		
Operating Junction and Storage Temperat	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40		
	Free Air (TO-220AB)		62.5	°C/W	
Junction-to-Case		R <sub>thJC</sub>	0.6		

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		·					
Drain-Source Breakdown Voltage	$V_{DS}$ $V_{GS} = 0 V, I_D = 250 \mu A$		100			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50		
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.009		-	
	В	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.020			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$		0.023		Ω	
		$V_{GS}$ = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.030			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A	25			S	
Dynamic <sup>b</sup>		•					
Input Capacitance	C <sub>iss</sub>			4700		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		665			
Reverse Transfer Capacitance	C <sub>rss</sub>			265			
Total Gate Charge <sup>c</sup>	Qg			105	160		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		17		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			12	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 0.6 $\Omega$		90	135		
Turn-Off DelayTime <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$		55	85	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			130	195		
Source-Drain Diode Ratings and Cha	racteristics T <sub>C</sub> :	= 25 °C <sup>b</sup>	•	•	•		
Continuous Current	ا <sub>S</sub>				85	•	
Pulsed Current	I <sub>SM</sub>				240	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			85	140	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dl/dt = 100 A/μs		4.5	7	А	
Reverse Recovery Charge	Q <sub>rr</sub>	1		0.17	0.35	μC	

Notes:

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55 °C

5

V<sub>GS</sub> = 10 V

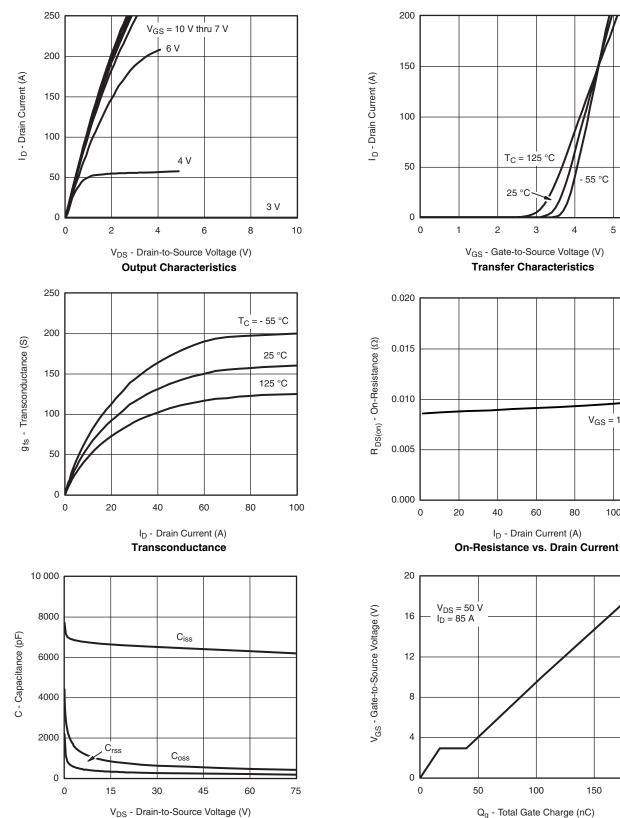
100

120

80

6

4



#### **TYPICAL CHARACTERISTICS** $T_A = 25 \text{ °C}$ , unless otherwise noted

Capacitance

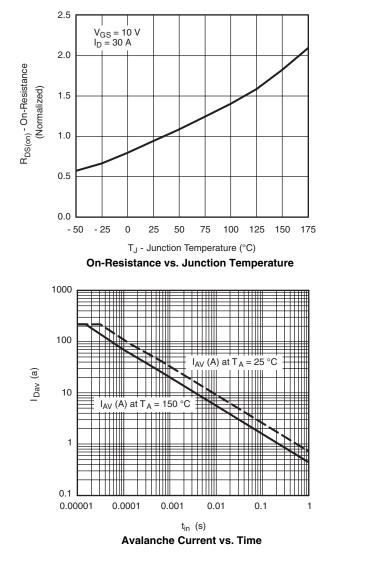
200

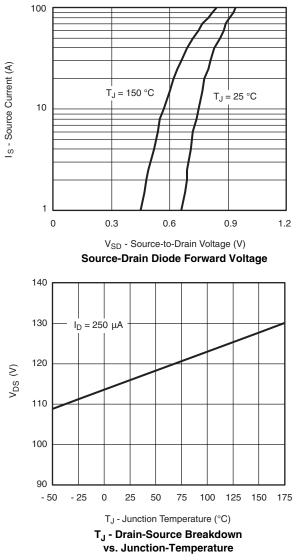
150

Gate Charge



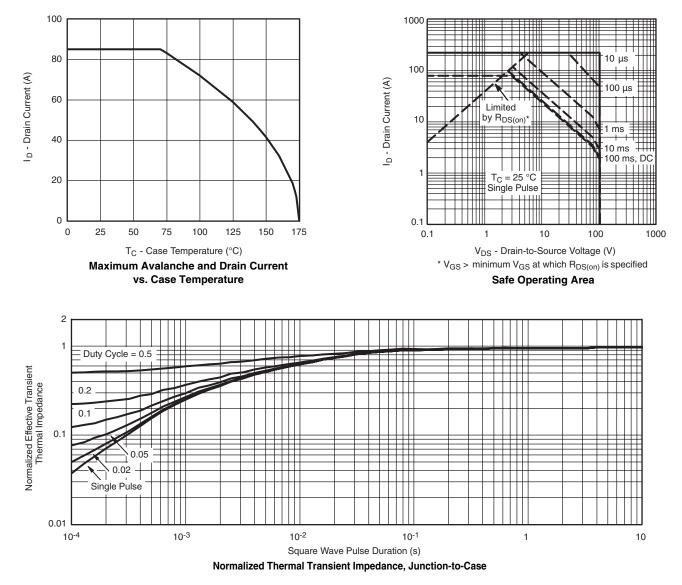
### **TYPICAL CHARACTERISTICS** $T_A = 25 \text{ °C}$ , unless otherwise noted





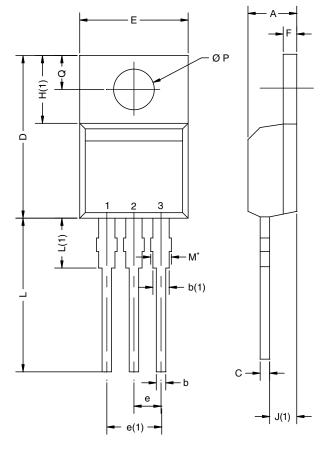


#### THERMAL RATINGS





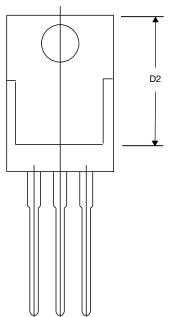
## TO-220AB



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
с	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

#### Note

\* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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